

300 mm wafer fab in Dresden

October 7, 2019
PI 11032 AE Fi/af

General information

- ▶ Total investment approx. 1 billion euros
- ▶ Site approx. 100,000 m²
(about 14 soccer fields)
- ▶ Total floor space approx. 72,000 m² of production area
and office space
- ▶ Construction timeline Groundbreaking in spring 2018,
installation of machinery mid-/end 2019,
pilot production to start at end of 2021
- ▶ Associates in the completed plant Up to 700
- ▶ Qualified professionals needed Experts from the semiconductor industry,
such as process, production, and
maintenance engineers, mathematicians,
software engineers, as well as
professionals with degrees in physics,
chemistry, and microsystems
technologies
- ▶ Manufacturing technology Highly automated wafer production
(300 mm silicon substrate wafers
with structures up to 65 nm in width –
1 nm equals one millionth of a millimeter)

- ▶ Connected manufacturing
Every second, the machines will transmit one gigabit of production data. The volume of data produced is equivalent to more than 42 million written sheets of paper, weighing 22 metric tons.

Details on the building

- ▶ Total building volume
600,000 m³
- ▶ Concrete
approx. 66,500 m³
(about 8,300 concrete mixer trucks)
- ▶ Steel
approx. 16,400 metric tons
(about 30 A380 passenger jets)
- ▶ Earth moved/excavated
approx. 90,000 m³
(some 7,500 truckloads)
- ▶ Bored piles for the foundation
approx. 860
- ▶ Floor slabs
100 cm thick
- ▶ Length of piping and ductwork
approx. 80 km
- ▶ Length of electrical cabling
approx. 380 km
(from Dresden to Berlin and back)

Internet

- ▶ For job seekers
www.bosch-career.de/jobs
- ▶ Site for the Dresden location
<https://www.bosch.de/en/our-company/bosch-in-germany/dresden/>
- ▶ Bosch semiconductors
www.bosch-semiconductors.com/